## PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	life.augmented	STMicroelectronics International N.V
1.2 PCN No.		POWER AND DISCRETE PRODUCTS/25/15254
1.3 Title of PCN		998G (TFME) - Mold Compound replacement and FE improvement (Industrial).
1.4 Product Category		Pls refer to the product list (SiC MOSFET)
1.5 Issue date		2025-03-17

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	PIKE EMMA	
2.1.2 Phone	+44 1628896111	
2.1.3 Email	emma.pike@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Angelo RAO	
2.1.2 Marketing Manager	Antonino GAITO	
2.1.3 Quality Manager	Vincenzo MILITANO	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials		998G (TFME) as assy Plant. 0152 ST Catania as FE plant.

4. Description of change			
	Old	New	
4.1 Description	Molding Compound: Kyocera KEG-300S-1 Single passivation and Square TEOS.	Molding Compound: HHCK EMG-400-C . Round Teos and Double Passivation.	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	processability		

5. Reason / motivation for change		
5.1 Motivation	Discontinuation of KYOCERA KEG-300S-1 production and FE process improvement.	
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change		
6.1 Description	New FGs	

7. Timing / schedule		
7.1 Date of qualification results	2024-11-30	
7.2 Intended start of delivery	2025-09-05	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description 15254 REPPTD24089_1.0_SiC SQKW in TO247 LL TFME with Resin EMG400C.rev.6.pdf			rev.6.pdf
8.2 Qualification report and qualification results		Issue Date	2025-03-17

9. Attachments (additional documentations)
15254 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No
	SCTWA90N65G2V	

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